Material Selection		Process Capabilities and Tolerances	
Polyimide Thickness	0.0005" (12 um), 0.001" (25 um), 0.002" (50 um), 0.003" (75 um), 0.005" (125 um)	Minimum Trace/Space	0.0015"/.002" (0.33 oz.) 0.002"/.0025" (0.5 oz.) 0.003"/.0035" (1 oz.)
Copper (thickness)	0.25 oz.(9 um), 0.33 oz.(12 um), 0.5 oz. (17 um), 1 oz.(35 um), 2 oz.(70 um)	Minimum Via Hole Diameter (before plating)	0.006" (NC Drill) 0.002" (UV Laser)
Copper Foils (rolled-annealed)	Polyimide, Polyester, LPI (liquid photo imageable), PIC(photo imageable cover coat)	Minimum Blind Via Diameter (before plating)	0.004" (UV Laser)
Stiffeners	FR-4, Polyimide, Metal, or customer supplied	Trace to Edge Distance	0.010" (NC Route) 0.008" (Die Punch) 0.001" (UV Laser)*
Thermo-bond Adhesives	Acrylic, Phenolic Butyral, Modified Epoxy	Trace to Edge Tolerance	0.005" (NC Route) 0.003" (Die Punch) 0.001" (UV Laser)
Surface Finishes	Solder (hot air leveling or tin/lead plating), Electrolytic Soft Bondable Gold, Hard Gold, ENIG (electroless nickel immersion gold), Entek 106A, & Immersion Tin	Cover Layer Aperture Positional Tolerance	0.005" (Cover Film) 0.002" (LPI and PIC) 0.001" (Laser Ablation)**

* Trace to edge distance should be greater than 0.003" for proper copper insulation
** Laser defined apertures created by ablating cover layer material